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IDS Form PTO/SB	/08: Substitute for form	1449A/PTO \			Complete if Known	
		•	To.	plication Number	10/644,745	
INFO	RMATION DI	SCLOSU	JRE MADE	Filing Date	August 21, 2003	
STA	TEMENT BY	APPLICA	NT	First Named Inventor	Hideki TANAKA	_
			4141	Art Unit	2878	_
	(Use as many sheets a:	s necessary)		Examiner Name	J. Lee	_
Sheet	1	of	1	Attorney Docket Number	07553.0044-00	

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Note: Submission of copies of U.S. Patents and published U.S. Patent Applications is not required.

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Examiner Initials	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	Translation ⁶	
JL	5	English Abstract of JP 64-081197		
JL	6	English Abstract of JP 2000-100795	†	
JL	7	English Abstract of JP 2001-319922		

Con-tract			
Examiner	/John Lee/ (01/05/2007)	Date	
Signature	/John Lee/ (01/05/2007)	Considered	